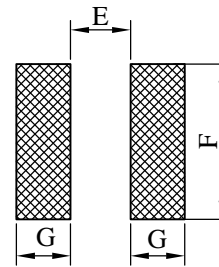
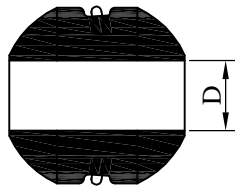
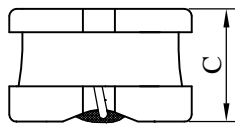
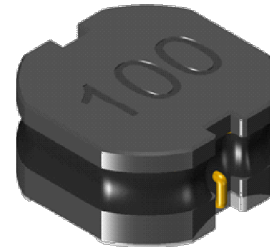
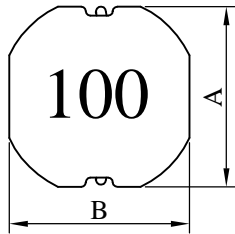


SPECIFICATION FOR APPROVAL

REF. :

PROD. NAME	Semi-shielded SMD Power Inductor	ABC'S DWG NO.		RN8040□□□□L□-□□□	
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I . Configuration and dimensions :



(PCB Pattern)

Unit : m/m

A	B	C	D	E	F	G
8.00 ±0.3	8.00 ±0.3	4.00 max.	3.20 ref.	3.00 ref.	8.20 ref.	2.60 ref.

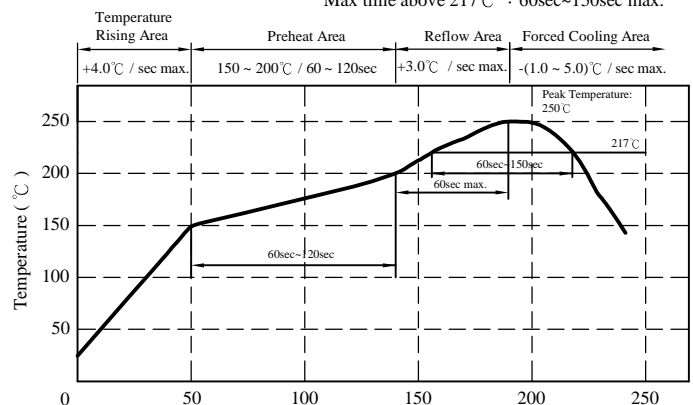
II . Description :

- a . Ferrite drum core construction.
- b . Magnetically epoxy.
- c . Enamelled copper wire : F or H class
- d . Product weight : 0.90 g (ref.)
- e . Moisture sensitivity Level 1
- f . Products comply with RoHS' requirements
- g . Halogen Free available

III . General specification :

- a . Storage temp. : -40°C ----+125°C
- b . Operating temp. : -40°C ----+125°C
(Temp. rise included)
- c . Resistance to solder heat : 250°C .10 secs.

Peak Temp : 250°C max.
Max. Peak Temp - 5°C : 30sec max.
Max time above 217°C : 60sec~150sec max.



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SPECIFICATION FOR APPROVAL

REF. :

PROD. NAME	Semi-shielded SMD Power Inductor	ABC'S DWG NO.		RN8040□□□□L□-□□□	
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IV . Electrical characteristics :

DWG No.	Inductance (uH)	RDC (mΩ)		Isat (A) max.	Irms (A) max.
		ref.	max.		
RN8040R50YL□-□□□	0.5±30%	5.7	7.0	12.00	10.00
RN80401R0YL□-□□□	1.0±30%	6.9	10.0	11.00	7.80
RN80401R5YL□-□□□	1.5±30%	8.6	11.0	8.20	7.00
RN80402R2YL□-□□□	2.2±30%	10.5	13.0	7.40	6.30
RN80402R7YL□-□□□	2.7±30%	16.2	21.0	5.50	5.60
RN80403R6YL□-□□□	3.6±30%	16.5	22.0	5.30	4.90
RN80404R7YL□-□□□	4.7±30%	18.3	24.0	4.70	4.10
RN80406R8YL□-□□□	6.8±30%	25.1	33.0	4.20	3.90
RN80408R2YL□-□□□	8.2±30%	35.0	45.0	4.00	3.70
RN8040100ML□-□□□	10.0±20%	37.6	50.0	3.40	3.10
RN8040150ML□-□□□	15.0±20%	53.6	70.0	2.70	2.40
RN8040220ML□-□□□	22.0±20%	76.3	100.0	2.20	2.20
RN8040330ML□-□□□	33.0±20%	112.0	145.0	1.90	1.70
RN8040470ML□-□□□	47.0±20%	145.0	190.0	1.50	1.40
RN8040680ML□-□□□	68.0±20%	212.0	275.0	1.20	1.10
RN8040101ML□-□□□	100.0±20%	310.0	400.0	1.00	1.00

- 1). □ : Packaging information : □ Code
- 2). "-□□□" : Reference code
- 3). Electrical specifications at 25°C
- 4). Inductance Test Condition. : 100kHz / 1V
- 5). Irms base on Temp. rise 40°C max.
- 6). Isat base on $\Delta L/L0A=30\%$ max.

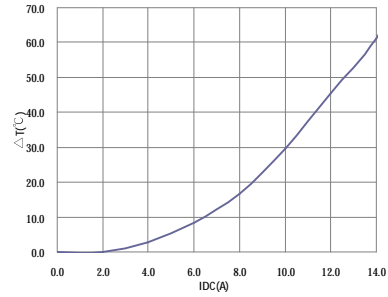
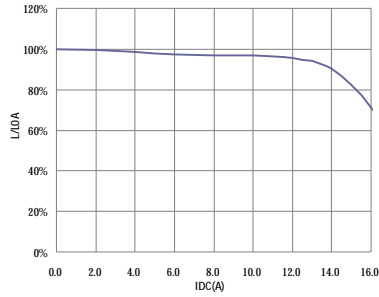
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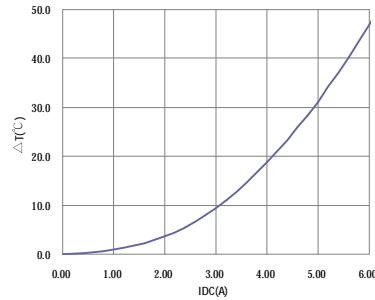
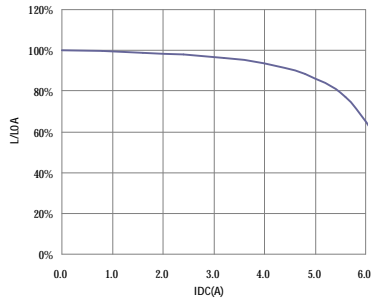
PROD. NAME	Semi-shielded SMD Power Inductor	ABC'S DWG NO.	RN8040□□□□L□-□□□		
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V . Curve :

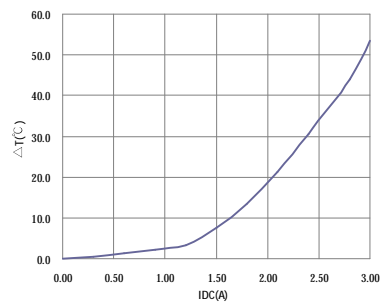
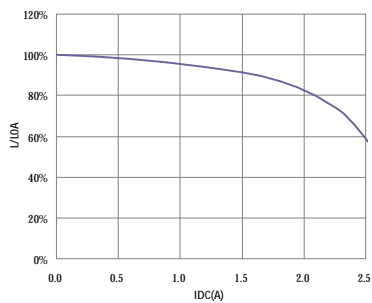
RN8040R50YL□



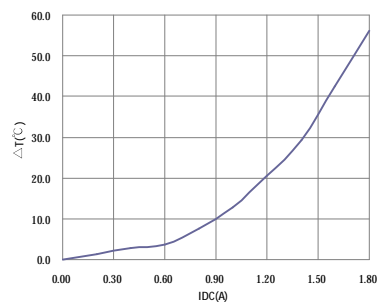
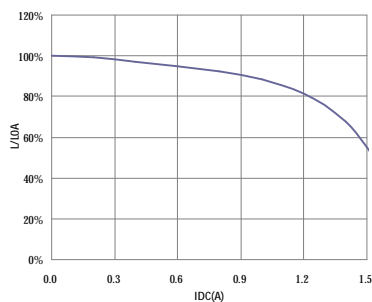
RN80404R7YL□



RN8040330ML□



RN8040101ML□



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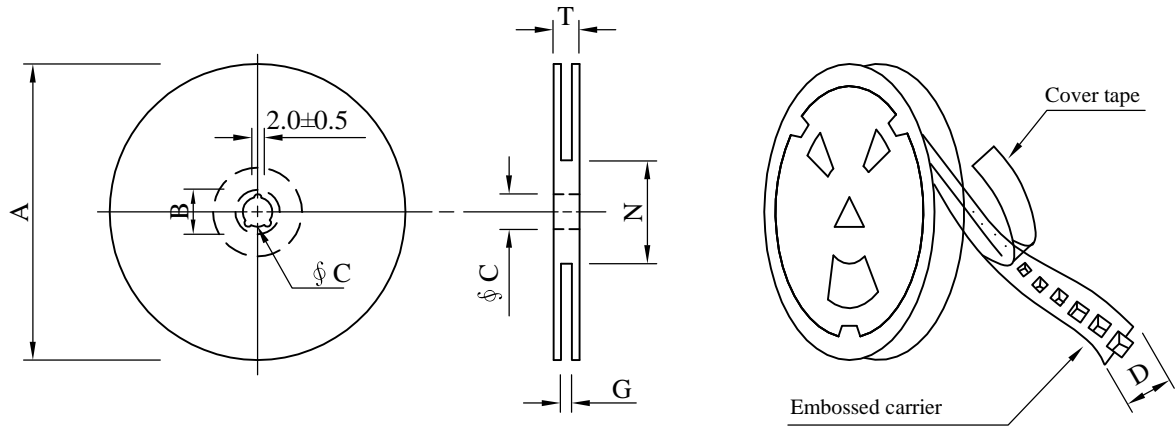
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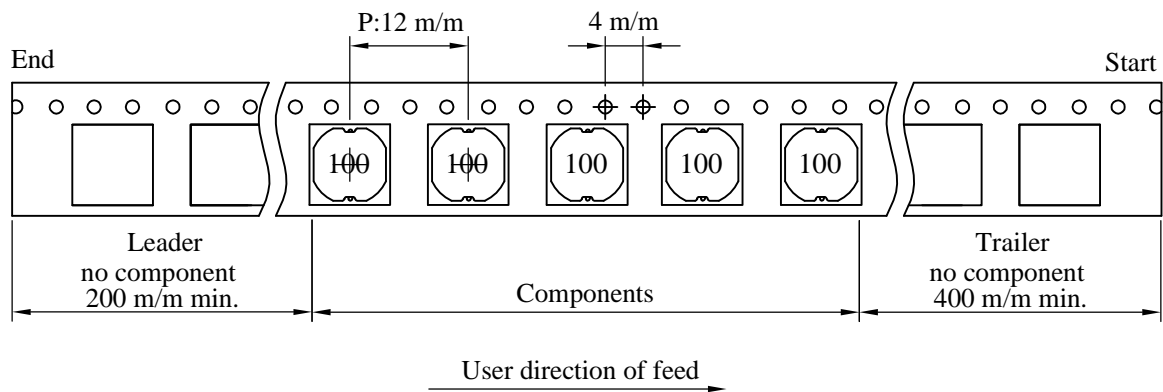
PROD. NAME	Semi-shielded SMD Power Inductor	ABC'S DWG NO.		RN8040□□□□L□-□□□	
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VI-1 . Packaging information :

(1) Configuration



※Carrier tape width : D



(2) Dimensions

Unit:m/m

Style	A	B	C	D	G	N	T
13 - 16	330	21±0.8	13±0.5	16	18 ⁺⁰	50 ⁻⁰	22.4

(3) Q'TY & G.W. Per package

Code	Inner : Reel			Outer : Carton		
	Q'TY (pcs)	G.W. (gw)	Style	Q'TY (pcs)	G.W. (Kg)	Size (cm)
B	1,200	1104	13 - 16	7,200	6.6	38 x 37 x 22

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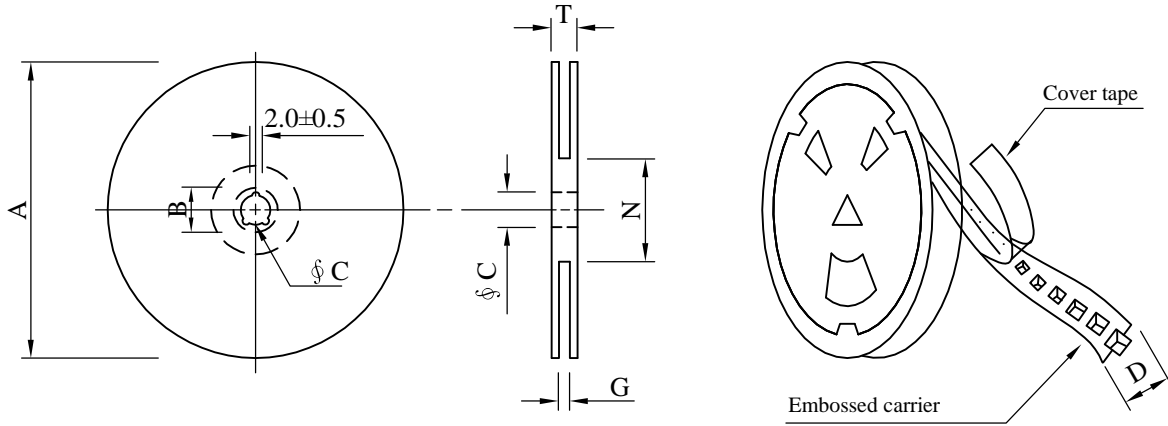
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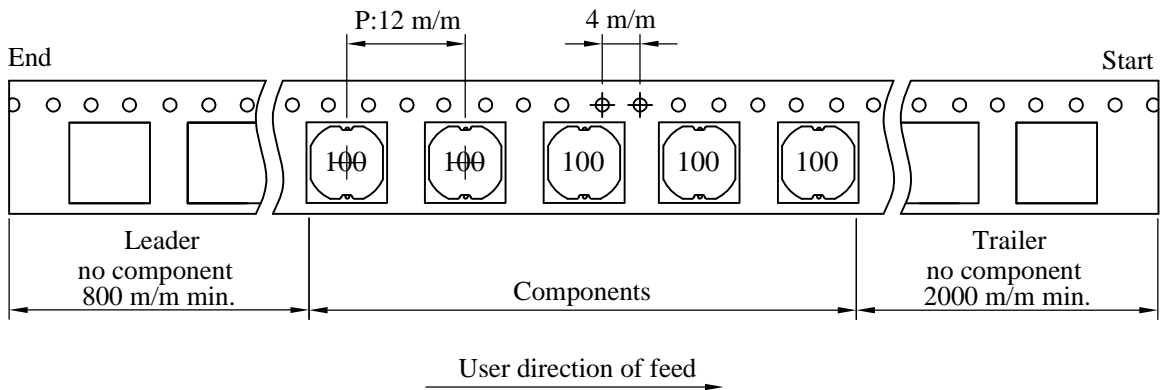
PROD. NAME	Semi-shielded SMD Power Inductor	ABC'S DWG NO.		RN8040□□□□L□-□□□	
		REV.	20160812-G	PAGE	4-2

VI-2 . Packaging information :

(1) Configuration



※Carrier tape width : D



(2) Dimensions

Unit:m/m

Style	A	B	C	D	G	N	T
13 - 16	330	21±0.8	13±0.5	16	18 ⁺⁰	50 ⁻⁰	22.4

(3) Q'TY & G.W. Per package

Code	Inner : Reel			Outer : Carton		
	Q'TY (pcs)	G.W. (gw)	Style	Q'TY (pcs)	G.W. (Kg)	Size (cm)
C	1,000	1,310	13 - 16	6,000	9.2	38 x 37 x 22

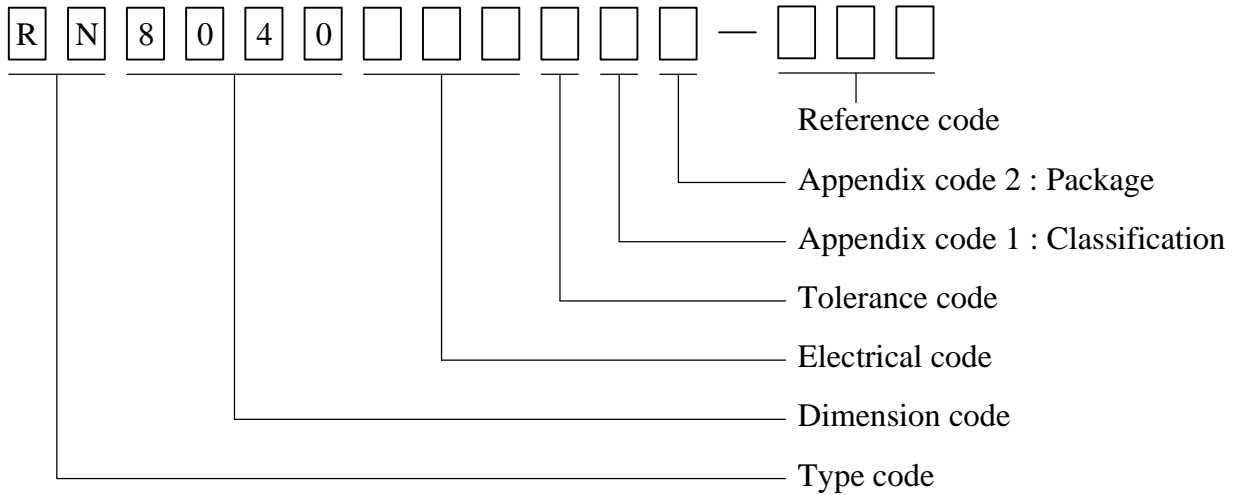
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SPECIFICATION FOR APPROVAL

REF. :

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VII . Drawing number expression :



Appendix code 1 : Product Classification

Appendix code 2 : Package Information

Code	Inner package	Cover tape	Carrier tape	Bag	Package Q'TY	Remark
B	T/R (Reel package)	UCT	Antistatic	Antistatic	1200 pcs	
C	T/R (Reel package)	UCT	Antistatic	Antistatic	1000 pcs	

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SPECIFICATION FOR APPROVAL

REF. :

PROD. NAME	Semi-shielded SMD Power Inductor	ABC'S DWG NO.	RN8040□□□□L□-□□□		
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VIII . Reliability test :

Item	Reference documents	Test Condition	Test Specification
1.High Temperature Exposure	MIL-STD-202 Method 108	1.Temperature: 125±2℃ 2.Time:96±2 hours.	1.No mechanical or electrical damage. 2.Inductance shall not change more than ±20%.
2.Temperature Cycling	JESD22-A 104	1.Temperature: -40℃ ~ +125℃ 2.Number of cycle:100 cycle 3.Dwell time:30 minutes	1.No mechanical or electrical damage. 2.Inductance shall not change more than ±20%.
3.Biased Humidity Test	MIL-STD-202 Method 103	1.Temperature : 85±2 ℃ 2.Humidity: 85% RH. 3.Time:96±2 Hours	1.No mechanical or electrical damage. 2.Inductance shall not change more than ±20%.
4.Operational Life	JESD22-A 108	1.Temperature: 125℃ (Temp. rise included) 2.Time:96±2 hours. 3.Rated current	1.No mechanical or electrical damage. 2.Inductance shall not change more than ±20%.
5.External Visual	JESD22-B 101 & MIL-STD-883 Method 2009	Inspect product constructions, marking and workmanship.	1.No pollution on the surface of products. 2.Clear marking. 3.No crack.
6.Physical Dimensions	JESD22-B 100	Verify physical dimensions to the applicable product detail specification.	Per product specification standard
7.Resistance to solvents	MIL-STD-202 Method 215	Immerse into solvent for 3±0.5 minutes & brush 10 times for 3 cycles.	1.No body change in appearance. 2.No marking blurred. 3.Inductance shall not change more than ±20%.
8.Vibration Test	MIL-STD-202 Method 204	1.Frequency and Amplitued : 10-2000-10 Hz, 1.5 mm. 2.Direction:X, Y, Z 3.Test duration:2 hours for each direction, 6 hours in total.	1.No mechanical or electrical damage. 2.Inductance shall not change more than ±20%.
9.Resistance To Soldering Heat Test	MIL-STD-202 Method 210 & J-STD020D.1	1.Highest temperature : 250±5℃. 2.Time (temp. ≥ 217℃) : 60~150 Seconds. 3.IR reflow times : 3 times.	1.No mechanical or electrical damage. 2.Inductance shall not change more than ±20%.
10.Saturation Current	JIS C 6436 & User SPEC.	1.Applied rated current for 5 seconds. 2.Saturation current	Inductance shall not drop more than 30% max.
11.Over load	JIS C 6436 & User SPEC.	1.Applied one and half rated current for a period of 5 minutes. 2.Rated current	No electrical or mechanical damage
12.Temperature Rise Current	JIS C 6436 & User SPEC.	1.Applied rated current for 10 minutes. 2.Temperature measure by digital surface thermometer. 3.Irms current	Surface temperature rise is less than 40℃ max.
13.Solderability Test	J-STD-002 & JESD22-B 102	1.Baking in pre-testing : 150±5℃ / 16Hours±30 min. 2.Peak temperature : 240±5℃ 3.Time (temp. ≥ 217℃) : 60~150 seconds. 4.IR reflow times : 1 time.	More than 95% soldering coverage min on terminations.
14.Electrical Characteriazation	MIL-STD-202 Method 304 & User SPEC.	1.Operating temperature : -40℃~125℃ 2.Room temperature : 25℃.	1.No mechanical or electrical damage. 2.Inductance shall not change more than ±20%.
15.Drop	CNS-C6354 & GB/T 2423.8	1.Products shall be mounted on SPEC. PCB and dropped down from a height of 1m 2.Drop total time : 6 times. (Every side of sample drop 2 times)	1. Adhesion on PCB shall be enough. 2. Product appearance shall not break. 3. No electrical damage.
16.Terminal Strength Test	IEC 60068-2-21	1.Apply push force to samples mounted on PCB. 2.Force of 1.8 kg for 60±1 seconds.	After test, inductors shall be no mechanical damage.

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